

# MiniLab

Leading in Vapor Phase Technology

Economy Vapor Phase Soldering Machine for Laboratory / Mini Series Produktion

**IBL**



## The Machine

The MiniLab reflow vapor phase soldering machine is perfect for small volume production and offers superior solder quality. It is ideal for development, NPI and prototype production as well as for soldering BGAs and LGAs.

## Overview

- Table-top unit with top loading
- Suitable for BGAs, stacked packages,...
- Oxygen-free soldering
- No overheating of components
- No  $\Delta T$ 's throughout the assembly

## Standard Equipment / Specification

- Fully automatic solder cycle
- Solder automatic
- Energy management system
- Fluid level check
- Observation window to process chamber

## Special features

- Maintenance-free transport system (**patented**)
- **Patented** flash-lock to process chamber while loading and unloading

## Options

- Adapter for double sided PCB boards
- ReSy, a device for repair of QFP's and BGA's
- Stainless steel grid for the workpiece carrier
- Closed-loop-chiller

Technical Data	MiniLab
Length (over all)	730 mm
Depth	620 mm
Height	640 mm
Weight	70 kg
Max. board size	300 x 275 x 80 mm
Liquid agent filling	2 kg
Water connection	1/2" / 2,5-5 bar / 0,5l/min
Max. heating capacity	1,8 kW
Ø power consumption/h	0,8 kW/h
Power supply	205-240 VAC, 2 KW
Main fuse	16 A, Typ "gL" or "C"

- Technical changes reserved -

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